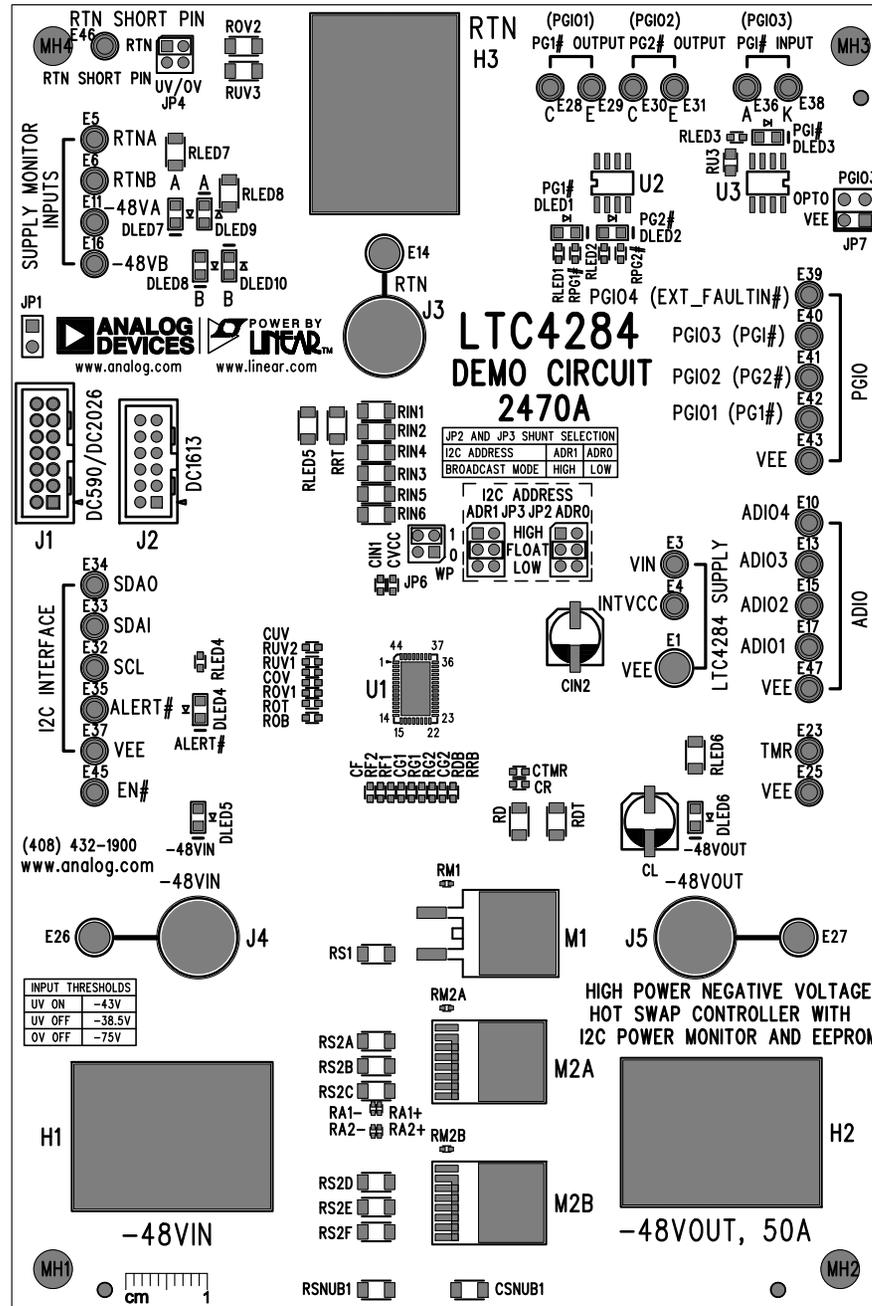


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	3	PRODUCTION	MANPREET S.	08-02-18

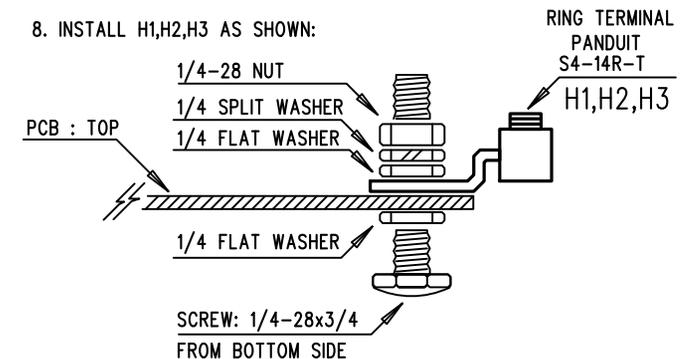


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL DLED1-DLED8 AS SHOW:



8. INSTALL H1,H2,H3 AS SHOWN:



APPROVALS		ANALOG DEVICES		POWER BY LINEAR	
PCB DES.	KIM T.	www.analog.com	www.linear.com	1630 McCARTHY BLVD. MILPITAS, CA 95035 TEL: (408)432-1900	
APP ENG.	SAL A.	TITLE: TOP ASSEMBLY DRAWING HIGH POWER NEGATIVE VOLTAGE HOT SWAP CONTROLLER WITH I2C POWER MONITOR AND EEPROM			
		SIZE	IC NO.	LTC4284IUHG	REV.
		N/A		DEMO CIRCUIT 2470A	3
		SCALE = NONE	FILENAME:	DC2470A-3.PCB	SHT 1 OF 2